

## **Thermal Test Report**

## Model Name : RM21706

## Rev : B



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#### 1. Executive Summary of Results

The Chenbro Micom RM21706 Rackmount Chassis provides adequate cooling for the Tyan S7010 motherboard with seven Western Digital 500GB SATAII Hard Drives and Dual 2.8GHz Intel Xeon X5560 processors.

Thermal Test	Test Results
Processor 1	Reference
Processor 2	Reference

Table 1 – Summary of Results

#### 2. Introduction

The purpose of this test is to ensure that the design of tested chassis model can pass the thermal goal under specific configuration which is either inquired or the most critical one.

The components examined during this test are processors. The Room Ambient Temperature (T-Room) is specified to 35 degree C.

This report has defined test configuration, test setup, test procedures and all the relevant modifications. The test result would be valid only when the same circumstance has been applied.

The test was done by Chenbro Micom Co., Ltd. which is located at following address:

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#### 3. Test Configuration

The tested system configuration is as following.

Component	Manufacturer	Model Number	Q'ty	Specification
Chassis	Chenbro	RM21706	1	Rackmount Server chassis
Main Board	Tyan	S7010	1	Full function
CPU Type	Intel	Intel®Xeon® X5560	2	2.8GHz Socket 1366
Memory	NANYA	NT2GC72B8PA0NF-CG	12	2GB.2RX8 1333.ECC
Chipset	Intel	X58	1	Full Function
VGA (on board)	ASPEED	AST2050	1	
Hard Drive	Western Digital	WD5002ABYS-01B1B0	4	SATA II 500GB
Hard Drive	Western Digital	WD5000ABPS-01ZZB0	2	SATA II 500GB
Hard Drive	Western Digital	WD5000ABYS-01YNA0	1	SATA II 500GB
RAID CARE	LSI	84016E	1	SAS/SATA Raid Card
CD-ROM	BENQ	DW200S	1	DVD ROM RW
PSU	3Y	YM-7501BAR	1	500W
System Fan (middle)	Y.S.TECH	FD128032HB	4	80x80x32/4400 RPM
CPU Cooler	Dynatron	G666	2	Active 2U Heatsink

Table 2 – System Configuration

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#### 4. Chassis Description (as Tested)

The RM21706 chassis is a Rackmount Server chassis that may ship with a 3Y 500W power supply (optional) and four system fans. It has one exposed CD-ROM drive bay, one internal 3.5" HDD drive bay and six 3.5" HDD hot-swap drive bays.

The dimensions of this chassis are 26"D x 16.9"W x 3.5"H

The chassis is manufactured by Chenbro Micom Co., Ltd. which is located at following address:

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#### 5. Test Equipment Used

#### **Thermal Chamber**

The thermal chamber's picture is as following. This thermal chamber can control the Room Ambient Temperature (T-Room) at 35 degree C.



Fig. 1 – Thermal Chamber

#### Thermocouples

T-type, 36AWG thermocouples are attached to the components.

#### **Data Acquisition System**

The picture of Data Acquisition System is as following. The Data Acquisition System includes one Agilent 34970A, 48 channel temperature recorder and one PC for logging the measured temperature data. The communication interface between recorder and PC is RS-232C.

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Fig. 2 - Data Acquisition System

#### 6. Support Software

The following software was used in this test.

- Power Thermal Utility for the Nehalem-EP Processor Rev1.0
- I/O Meter. Rev.2003.05.10
- Agilent BenchLink Data Logger Rev.1.5.030305.
- Intel Frequency Display
- Windows XP + SP2

#### 7. Test Setup and Procedure

- · Installation of the tested system
- · Installation of the operating system with device drivers
- Installation of the stress software utilities
- Installation of the thermocouples
- Place the tested system into thermal chamber
- · Power up the tested system
- Run the processor stress utility at 100% loading for both processors
- Run the utilities of the other devices such as HDD for simulating maximum loading
- Run the Data Logging Software to record the measurements
- Power on the process controller on the thermal chamber and control the room ambient at 35 degree C
- After the measured temperatures are settled, record the test duration and analyze the measurements.

#### 8. Test Results

#### Summary

With Power Thermal Utility for the Nehalem-EP Processor Rev1.0 running, the case temperature of processors did not exceed the specification for the Dual 2.8GHz Intel Xeon X5560 processors under specified configuration. Intel Frequency Display window did NOT have the instant warning message (to present the over-heat status includes message color changed).

#### Detail

Measured Points	Max. Specified	Measurements	Compensated
	Temp Limit (deg C)	@35 (deg C)	Data* (deg C)
1.T-CASE 1	Reference	N/A	Appendix D
2.T-CASE2	Reference	N/A	Appendix D
3.T-A1	Reference	40.5	40.2
4.T-A2	Reference	42.3	42.0
5.VRM-1	105	59.7	59.4
6.VRM-2	105	54.2	53.9
7.Memory-1	Reference	50.9	50.6
8.Mmeory-2	Reference	54.2	53.9
9.North Bridge	99	60.6	60.3
10.South Bridge	115	73.3	73.0
11.RAID CARD	Reference	83.6	83.3
12.HDD-1	55	44.3	44.0
13.HDD-2	55	41.8	41.5
14.T-ROOM	35	35.3	35.0

Table 3 - Detail of Test Results

\*Compensated Data = Measurement+(35–T-Room) = Measurement+(35–35.3)

= Measurement -0.3

#### Test Duration: 24 hours.

#### 9. Conclusion

The RM21706 chassis (as tested) does provide adequate cooling for the Dual 2.8GHz Intel Xeon X5560 processors.

The maximum temperatures of processors, which were at 100% loading of processor stress utility under 35 degree C room ambient. The most important part of the test result was that Intel Frequency Display window did NOT present the warning message.

The tested system does not necessarily represent the absolute worst-case that the system is subject to.

The system is not maximally loaded with add-in cards and their associated cables that could cause the internal temperatures to increase and reroute airflow.

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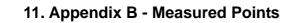
#### 10. Appendix A - System Setup

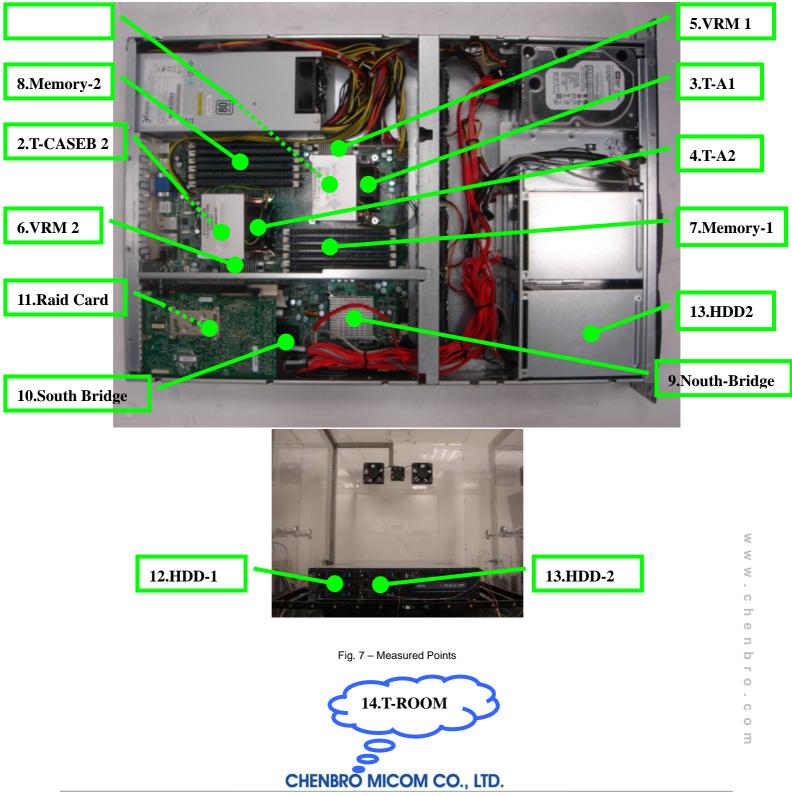


Fig. 3 - System Setup

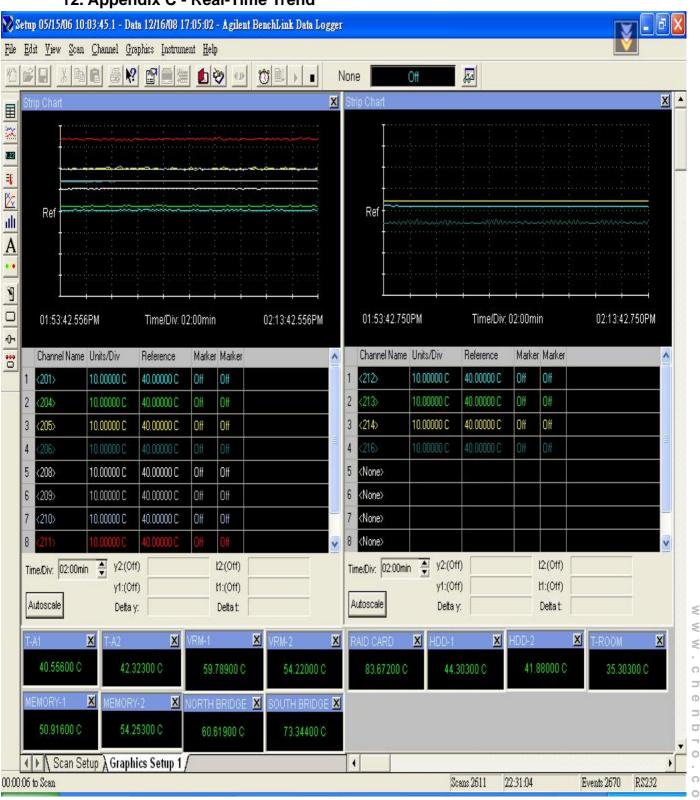
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## 12. Appendix C - Real-Time Trend

Fig.8 – Real-Time Trend

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#### 13. Appendix D - Intel Frequency Display

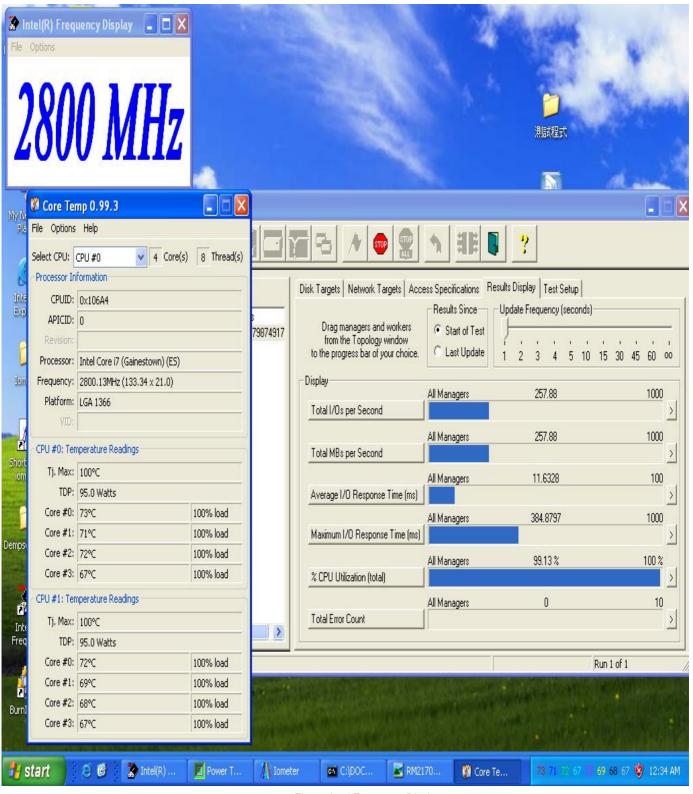


Fig. 9– Intel Frequency Display

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